Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

# 2SK2749

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain-source ON resistance  $: R_{DS (ON)} = 1.6 \Omega \text{ (typ.)}$ • High forward transfer admittance  $: |Y_{fs}| = 5.0 \text{ S (typ.)}$ 

• Low leakage current :  $IDSS = 100 \mu A \text{ (max) (VDS} = 720 \text{ V)}$ 

• Enhancement-mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	900	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	900	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	7	Α	
	Pulse (Note 1)	I <sub>DP</sub>	21	ı	
Drain power dissipatio	n (Tc = 25°C)	$P_{D}$	150	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	682	mJ	
Avalanche current		I <sub>AR</sub>	7	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

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Weight: 4.6 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 25.5 mH,  $I_{AR}$  = 7 A,  $R_G$  = 25  $\Omega$ 

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

2SK2749



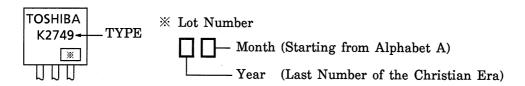
## **Electrical Characteristics (Ta = 25°C)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V <sub>(BR)</sub> GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	١	V
Drain cut-off cur	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 720 V, V <sub>GS</sub> = 0 V	-	_	100	μA
Drain-source br	eakdown voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	900	_	_	٧
Gate threshold v	roltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	٧
Drain-source OI	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.5 A	_	1.6	2.0	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.5 A	1.25	5.0	_	S
Input capacitance		C <sub>iss</sub>		_	1500	_	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	30	_	pF
Output capacitance		Coss		_	140	_	
Switching time	Rise time	t <sub>r</sub>	$V_{\rm GS}$ $10V_{\rm OV}$ $I_{\rm D}=3.5A_{\rm O}$ $V_{\rm OUT}$ $R_{\rm L}=114\Omega$ $V_{\rm DD}=400V$	_	35	_	- ns
	Turn-on time	t <sub>on</sub>		_	80	_	
	Fall time	t <sub>f</sub>		_	50	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu \text{s}$	_	220	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	55	_	
Gate-source charge		$Q_{gs}$	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$		30	_	nC
Gate-drain ("miller") Charge		$Q_{gd}$			25	_	

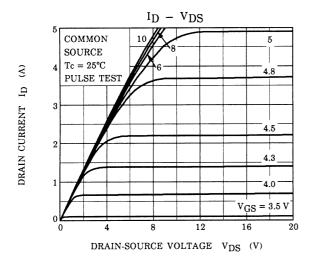
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

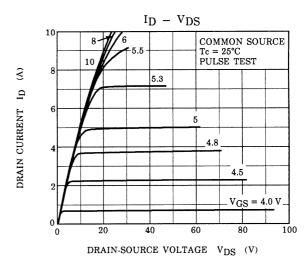
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	7	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	21	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 7 A, V <sub>GS</sub> = 0 V	-	_	-1.9	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 7 A, V <sub>GS</sub> = 0 V	_	1400	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 100 A / μs	_	14	_	μC

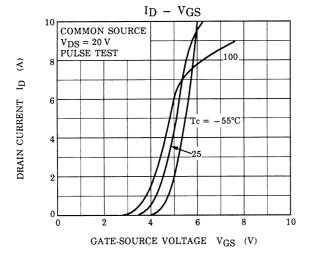
# Marking

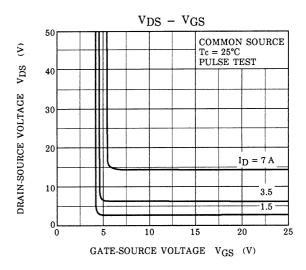


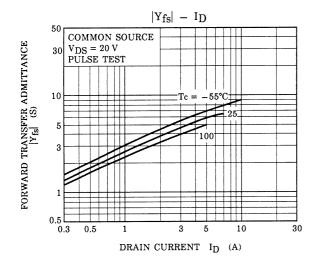
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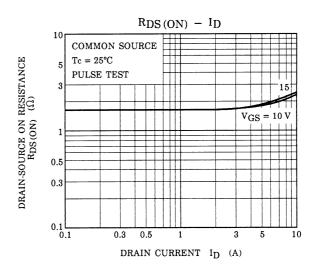




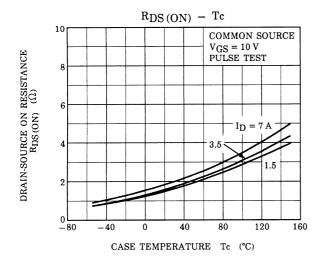


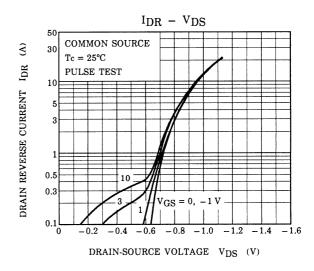


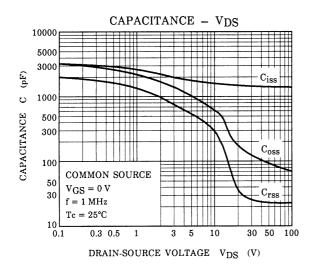


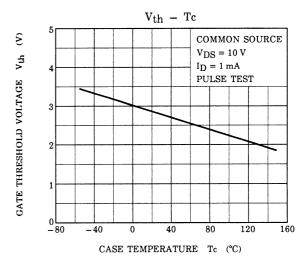


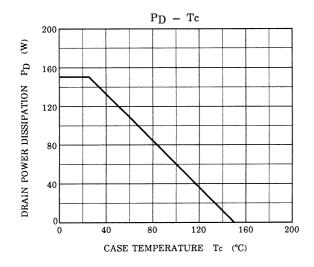
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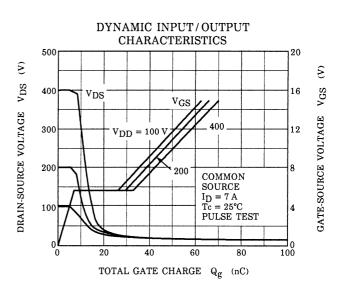




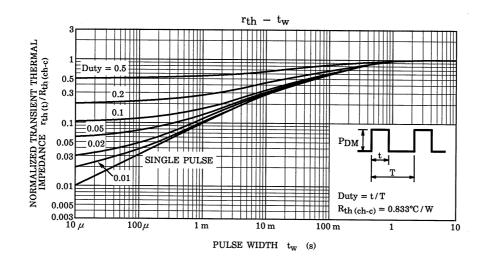


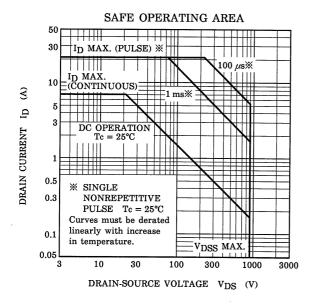


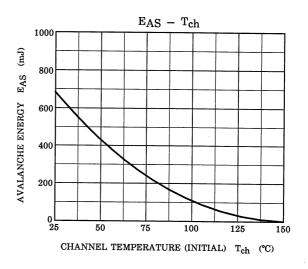


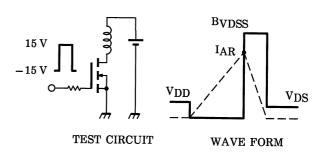


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$$\begin{aligned} &RG = 25 \ \Omega \\ &V_{DD} = 90 \ V, \ L = 25.5 \ mH \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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